

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claims 1-6 (canceled).

Claim 7 (currently amended): A surface mountable device comprising;  
a substrate including a first principal surface, a second principal surface, and a side surface connecting the first principal surface to the second principal surface;  
a terminal electrode disposed on the first principal surface; and  
a first conductor for appearance inspection extending continuously from the terminal electrode to the side surface and having a width less than a width of the terminal electrode; wherein  
the terminal electrode is arranged to be directly connected to a land on a mother board via solder; and  
the first conductor for appearance inspection is arranged such that the solder connecting the terminal electrode to the land extends from the terminal electrode onto the first conductor for appearance inspection.

Claim 8 (previously presented): The surface mountable device according to claim 7, further comprising a second conductor for appearance inspection disposed on the side surface of the substrate, the second conductor for appearance inspection being arranged to be continuous from an extended end of the first conductor for appearance inspection.

Claim 9 (previously presented): The surface mountable device according to claim 8, wherein the second conductor for appearance inspection extends in a direction that is substantially perpendicular to the first conductor for appearance inspection.

Claim 10 (previously presented): The surface mountable device according to claim 8, wherein the first conductor for appearance inspection and the second conductor for appearance inspection are arranged in a T shape.

Claim 11 (previously presented): The surface mountable device according to claim 8, wherein a dimension of the second conductor for appearance inspection in a horizontal direction is about 100  $\mu\text{m}$  to about 300  $\mu\text{m}$

Claim 12 (previously presented): The surface mountable device according to claim 7, wherein a width of the first conductor for appearance inspection is about 100  $\mu\text{m}$  or less.

Claim 13 (previously presented): The surface mountable device according to claim 7, wherein a height of the first conductor for appearance inspection is about 100  $\mu\text{m}$ .

Claim 14 (previously presented): The surface mountable device according to claim 7, wherein the first conductor for appearance inspection extends from the terminal electrode to the inside of the substrate.

Claim 15 (previously presented): The surface mountable device according to claim 7, wherein at least two first conductors for appearance inspection are disposed continuously at the terminal electrode.

Claim 16 (previously presented): The surface mountable device according to claim 11, wherein said at least two first conductors for appearance inspection are disposed continuously at both ends of the terminal electrode.

Claim 17 (previously presented): The surface mountable device according to claim 16, wherein said at least two first conductors extend upward from both ends of the

terminal electrode at an oblique angle with respect to the terminal electrode.

Claim 18 (previously presented): The surface mountable device according to claim 16, further comprising at least two second conductors for appearance inspection disposed on the side surface of the substrate, the at least two second conductors for appearance inspection being continuous from the extended ends of the at least two first conductors for appearance inspection.

Claim 19 (previously presented): The surface mountable device according to claim 18, wherein said at least two second conductors for appearance inspection extend in a substantially horizontal direction.

Claim 20 (previously presented): The surface mountable device according to claim 7, wherein a gold plating is disposed on said first conductor for appearance inspection.

Claim 21 (previously presented): The surface mountable device according to claim 7, wherein a gold plating is disposed on said terminal electrode.

Claim 22 (previously presented): The surface mountable device according to claim 7, wherein a gold plating is disposed on said first conductor for appearance inspection and said terminal electrode.